



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2015-03-25
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Flavio Di Francesco	<b>Representative Title</b>	AMS Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	LDO7*0358AE6	A	BO2A	2015-03-25
Amount	UoM	Unit type	ST ECOPACK Grade	
80.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.85 - 3.9 - 1.52	8	gull wing	
Comment	Package: SO 08 .15 JEDEC; MD valid for LM258AWDT; LM158WDT; LM258WDT; LM2904WDT; LM2904WHDT;LM358AWDT;LM358WDT			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	<b>true</b>
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th December 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				<b>true</b>
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	LDO7*0358AE6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies	Other inorganic materials	1.027	mg	supplier	die	Silicon (Si)	7440-21-3		1.010	mg	983447	12625
Die or Dies				supplier	metallization	Aluminium (Al)	7429-90-5		0.008	mg	7790	100
Die or Dies				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.004	mg	3895	50
Die or Dies				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.005	mg	4869	63
Leadframe	Copper & its alloys	33.756	mg	supplier	alloy	Copper (Cu)	7440-50-8		33.477	mg	991735	418463
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.015	mg	444	188
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.028	mg	829	350
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		0.236	mg	6991	2950
Die attach	Other inorganic materials	0.423	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		0.385	mg	910165	4813
Die attach				supplier	glue or tape	acrylate	Proprietary		0.021	mg	49645	263
Die attach				supplier	glue or tape	Methacrylate	Proprietary		0.017	mg	40189	213
Bonding wire	Other inorganic materials	0.051	mg	supplier	wire	Copper (Cu)	7440-50-8		0.051	mg	1000000	638
encapsulation	Other inorganic materials	43.763	mg	supplier	mold compound	Silica, vitreous	60676-86-0		37.626	mg	859767	470325
encapsulation				supplier	mold compound	Epoxy resin A	EC 413-900-7		1.717	mg	39234	21463
encapsulation				supplier	mold compound	Epoxy resin B	29690-82-2		1.717	mg	39234	21463
encapsulation				supplier	mold compound	phenol resin	Proprietary		1.287	mg	29408	16088
encapsulation				supplier	mold compound	carbon black	1333-86-4		0.129	mg	2948	1613
encapsulation				supplier	mold compound	additive	Proprietary		1.287	mg	29408	16088
connections coating	Solder	0.980	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.980	mg	1000000	12250